

**AMENDMENTS TO THE ABSTRACT:**

Please amend the abstract as follows:

Disclosed is a method of forming bump electrodes on wired circuit boards ~~wired board~~  
~~with a bump electrode whose production efficiency is improved.~~ A high-concentration  
impurity Si template doped with boron and having a pit formed therein is prepared. A plated  
resist is formed on the high-concentration impurity Si template and an opening is formed in  
~~portion for~~ at the position of the pit. Then, an electric field is applied to the high-concentration  
impurity Si template and Au is buried in the opening in the plated resist to form a Au-plated  
buried layer. An electrode pad is formed on a semiconductor chip. With the plated resist  
separated from the high-concentration impurity Si template, the electrode pad of the  
semiconductor chip is aligned with the Au-plated buried layer and is bonded by thermo-  
compression bonding. The Au-plated buried layer is transferred to the electrode pad to form an  
Au bump on the semiconductor chip.

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